



BTS - V - (S) - 06 - 037 (D)

**B. Tech Degree V Semester (Supplementary) Examination,
August 2006**

EC 503 MICROELECTRONICS & INTEGRATED CIRCUITS

(1998 Admission)

Time : 3 Hours

Maximum Marks : 100

- I. Explain the following processing steps used in the fabrication of ICs.
- (a) Epitaxial growth
 - (b) Photolithography
 - (c) Isolation technique
 - (d) Metallization. (20)
- OR**
- II. (a) What are the prime differences between Monolithic, thin film and thick film technologies? (6)
- (b) Describe different steps involved in the production of Electronic Grade Silicon. (14)
- III. (a) What are the different fabrication steps for an NMOS transistor? Draw the cross sectional view. (14)
- (b) Compare the performance of n-channel MOSFET over P. channel MOSFET. (6)
- OR**
- IV. (a) How isolation is achieved between transistors in MOS technology? (8)
- (b) Explain the fabrication steps of a Monolithic JFET structure. (12)
- V. (a) Explain the working of a supply independent Bipolar Transistor current source. (10)
- (b) Write short notes on DC level translators. (10)
- OR**
- VI. (a) Explain the working of a MOSFET current source. (10)
- (b) Explain the working of any one of the constant voltage source. (10)
- VII. Explain the following methods used for thin film processing
- (i) Vacuum Evaporation
 - (ii) DC Cathode Sputtering
 - (iii) Vapour - Phase Deposition
 - (iv) Plating Techniques (20)
- OR**
- VIII. (a) Discuss the structure and characteristics of planar wave guides. (8)
- (b) Explain any one type of optical switch. (6)
- (c) Compare thin film and thick film devices. (6)
- IX. (a) Write short notes on PLD and PLA. (6)
- (b) Explain the operation of a CCD memory with the help of a neat diagram. (7)
- (c) Explain the operation of I²L inverter. (7)
- OR**
- X. (a) Distinguish between RAM, ROM and EPROM based on their fabrication. (8)
- (b) Explain the significance of ASICs. (7)
- (c) Discuss briefly about FPGA. (5)
